

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Re Application of :

Daisuke Nakamura et al :

Filed: Herewith :

For: HEAT DISSIPATING STRUCTURE OF PRINTED  
CIRCUIT BOARD AND FABRICATING METHOD THEREOF

**PRELIMINARY AMENDMENT A**

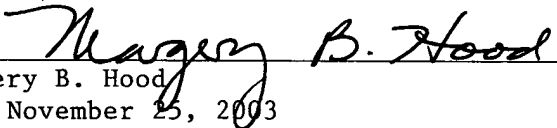
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Sir:

Please preliminarily amend the above-referenced application  
as follows:

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Margery B. Hood

Dated: November 25, 2003